

DESCRIPTION

The MP62180/MP62181 Power Distribution Switch features internal current limiting to prevent damage to host devices due to faulty load conditions. The MP62180/MP62181 operates from a 3.3V or 5V nominal input voltage and includes an 85mΩ Power MOSFET to handle up to 2A continuous load with a 2.8A typical current limit. The MP62180/MP62181 has built-in protection for both over current and increased thermal stress. For over-current protection (OCP), the device will limit the current by going into a constant current mode.

When continuous output overload condition exceeds power dissipation of the package, the thermal protection will shut the part off. The device will recover once the device temperature reduces to approx 120°C.

The MP62180/MP62181 is available in QFN8E, MSOP8E and SOIC8 packages.

FEATURES

- 2A Continuous Current
- 2.8A accurate Current Limit
- 2.7V to 5.5V Supply Range
- 90uA Quiescent Current
- 75mΩ MOSFET
- Thermal-Shutdown Protection
- Under-Voltage Lockout
- 8ms FLAG Deglitch Time
- No FLAG Glitch During Power Up
- Reverse Current Blocking
- Active High & Active Low Options

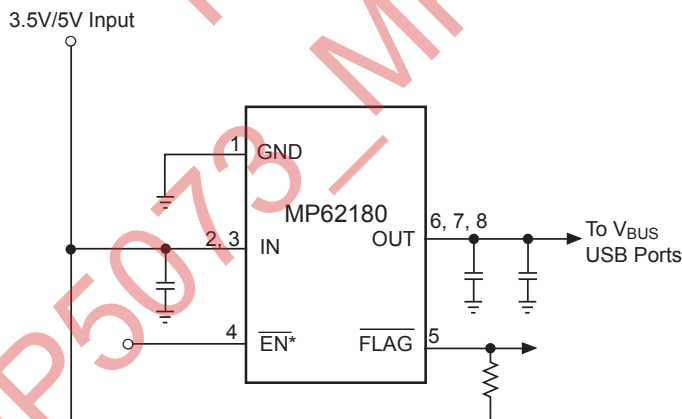
APPLICATIONS

- Smartphone and PDA
- Portable GPS Device
- Notebook PC
- Set-top-box
- Telecom and Network Systems
- PC Card Hot Swap
- USB Power Distribution

All MPS parts are lead-free, halogen free, and adhere to the RoHS directive. For MPS green status, please visit MPS website under Quality Assurance.

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TYPICAL APPLICATION



SINGLE-CHANNEL
* EN is active high for MP62181

ORDERING INFORMATION

Part Number	Enable	Switch	Maximum Continuous Load Current	Typical Short-Circuit Current @ T _A =25°C	Package	Top Marking	Free Air Temperature (T _A)
MP62180DS	Active Low	Single	2A	2.8A	SOIC8	62180DS	-40°C to +85°C
MP62180DD					QFN8E (2mm x 3mm)	62180DD	
MP62180DH					MSOP8E	62180DH	
MP62181DH	Active High	MSOP8E	62181DH				

Notes: NRFND for MP62180

* For Tape & Reel, add suffix -Z (e.g. MP62181DH-Z).

For RoHS Compliant Packaging, add suffix -LF (e.g. MP62181DH-LF-L)

PACKAGE REFERENCE

TOP VIEW	TOP VIEW	TOP VIEW
<p>MSOP8E</p>	<p>QFN8E (2mm x 3mm)</p>	<p>SOIC8</p>
MP62180 *: EN is active high for MP62181		

ABSOLUTE MAXIMUM RATINGS ⁽¹⁾

IN	-0.3V to +6.0V
EN, FLAG, OUT to GND	-0.3V to +6.0V
Continuous Power Dissipation (T _A = +25°C) ⁽²⁾	
MSOP8E	2.3W
QFN8E (2mm x 3mm)	2.3W
SOIC8	1.4W
Junction Temperature	150°C
Lead Temperature	260°C
Storage Temperature	-65°C to +150°C
Operating Temperature	-40°C to +85°C

Thermal Resistance ⁽³⁾

	θ_{JA}	θ_{JC}
MSOP8E	55	12
QFN8E (2mm x 3mm)	55	12
SOIC8	90	42

Notes:

- Exceeding these ratings may damage the device.
- The maximum allowable power dissipation is a function of the maximum junction temperature T_J(MAX), the junction-to-ambient thermal resistance θ_{JA} , and the ambient temperature T_A. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P_D(MAX)=(T_J(MAX)-T_A)/ θ_{JA} . Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- Measured on JESD51-7, 4-layer PCB.

ELECTRICAL CHARACTERISTICS ⁽⁴⁾
 $V_{IN}=5V$, $T_A=+25^{\circ}C$, unless otherwise noted.

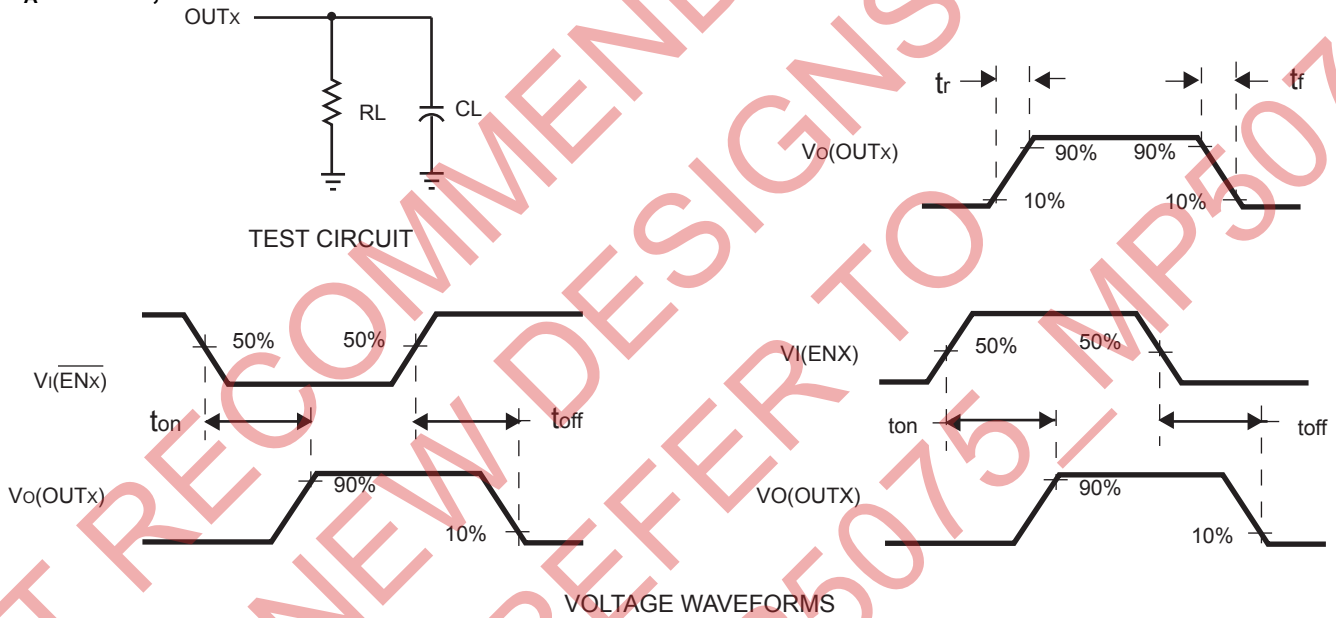
Parameter	Condition	Min	Typ	Max	Units
IN Voltage Range		2.7		5.5	V
Supply Current	Device Active, $I_{OUT}=0$		90	120	μA
Shutdown Current	Device Disable, $V_{OUT}=\text{float}$, $V_{IN}=5.5V$		1		μA
Off Switch Leakage	Device Disable, $V_{IN}=5.5V$		1		μA
Current Limit		2.1	2.8	3.5	A
Trip Current	Current Ramp (slew rate $\leq 100A/s$) on Output		3.1	4	A
Under-voltage Lockout	Rising Edge	1.95		2.65	V
Under-voltage Hysteresis			250		mV
FET On Resistance	$I_{OUT}=100mA$ ($-40^{\circ}C \leq T_A \leq 85^{\circ}C$)				
	MSOP8E		75	120	m Ω
	QFN8E (2mm x 3mm)		75	120	m Ω
	SOIC8		85	130	m Ω
EN Input Logic High Voltage		2			V
EN Input Logic Low Voltage				0.8	V
FLAG Output Logic Low Voltage	$I_{SINK}=5mA$			0.4	V
FLAG Output High Leakage Current	$V_{IN}=V_{FLAG}=5.5V$			1	μA
Thermal Shutdown			140		$^{\circ}C$
Thermal Shutdown Hysteresis			20		$^{\circ}C$
V_{OUT} Rising Time, T_r ⁽⁵⁾	$V_{IN}=5.5V$, $C_L=1\mu F$, $R_L=5\Omega$		0.9		ms
	$V_{IN}=2.7V$, $C_L=1\mu F$, $R_L=5\Omega$		1.7		ms
V_{OUT} Falling Time, T_f ⁽⁶⁾	$V_{IN}=5.5V$, $C_L=1\mu F$, $R_L=5\Omega$			0.5	ms
	$V_{IN}=2.7V$, $C_L=1\mu F$, $R_L=5\Omega$			0.5	ms
Turn On Time, T_{on} ⁽⁷⁾	$C_L=100\mu F$, $R_L=5\Omega$			3	ms
Turn Off Time, T_{off} ⁽⁸⁾	$C_L=100\mu F$, $R_L=5\Omega$			10	ms
FLAG Deglitch Time		4	8	15	ms
EN Input Leakage		-1			μA
Reverse Leakage Current	OUT=5.5V, IN=GND		0.2		μA

NOTE:

- 4) Production test at $+25^{\circ}C$. Specifications over the temperature range are guaranteed by design and characterization.
- 5) Measured from 10% to 90%.
- 6) Measured from 90% to 10%.
- 7) Measured from (50%) EN signal to (90%) output signal.
- 8) Measured from (50%) EN signal to (10%) output signal.

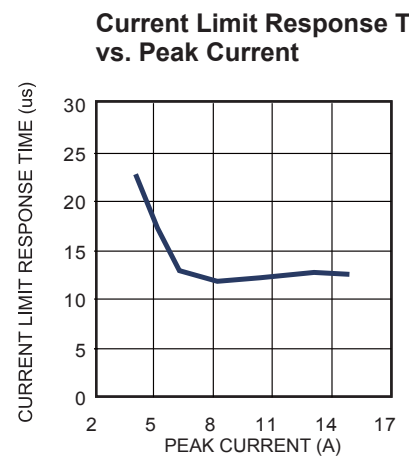
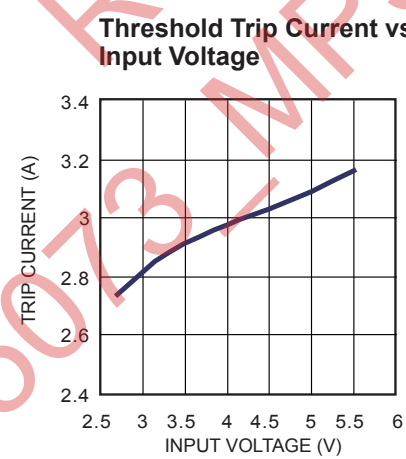
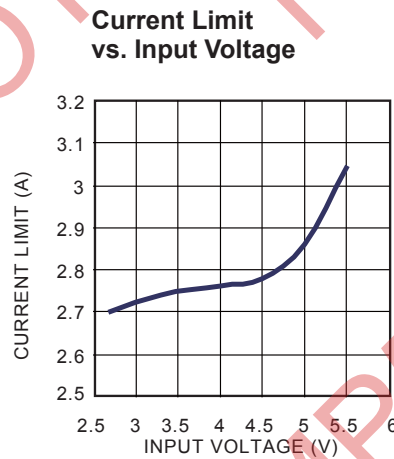
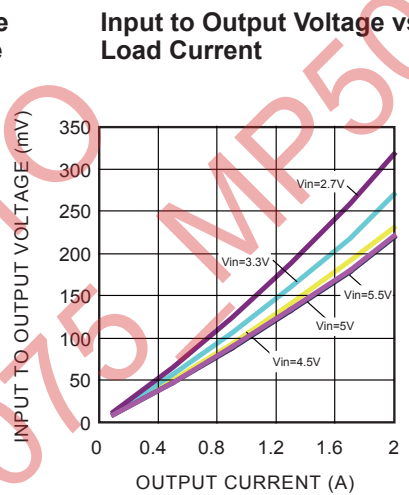
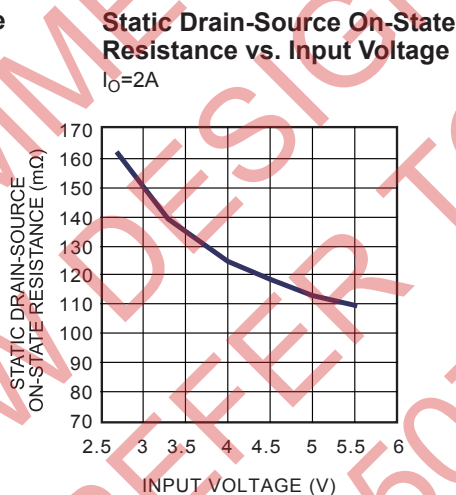
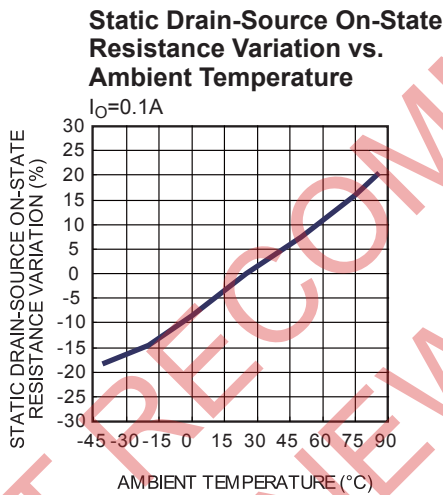
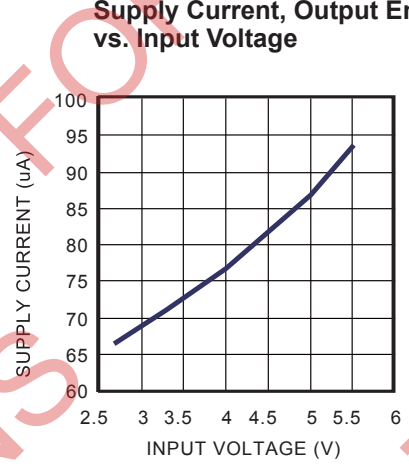
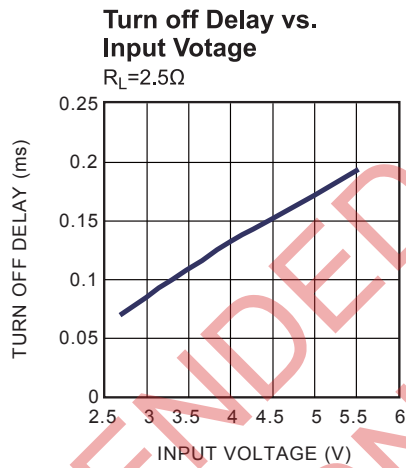
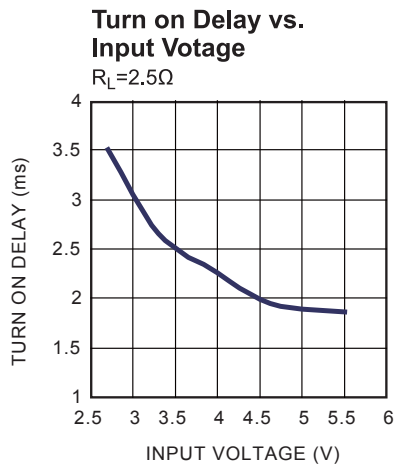
PIN FUNCTIONS

Pin # SOIC8	Pin # MSOP8E	Pin # QFN8E	Name	Description
1	1	1	GND	Ground.
2, 3	2, 3	2, 3	IN	Input Voltage. Accepts 2.7V to 5.5V input.
4	4	4	$\overline{\text{EN}}$	Active Low: (MP62180), Active High: (MP62181)
5	5	5	$\overline{\text{FLAG}}$	IN-to-OUT Over-current, active-low output flag. Open-Drain.
6, 7, 8	6, 7, 8	6, 7, 8	OUT	IN-to-OUT Power-Distribution Output (for all 3 output pins)

TYPICAL PERFORMANCE CHARACTERISTICS
 $T_A = +25^\circ\text{C}$, unless otherwise noted.

Figure 1—Test Circuit and Voltage Waveforms

TYPICAL PERFORMANCE CHARACTERISTICS

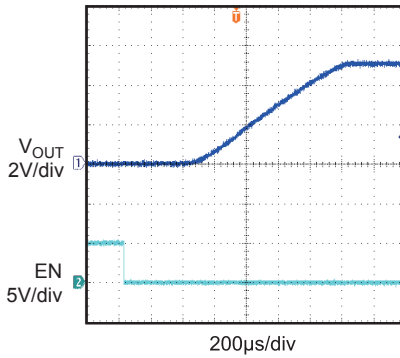
$V_{IN} = 5V$, $V_{EN} = 0V$ for MP62180 or 5V for MP62181, $C_L = 2.2\mu F$, $T_A = +25^\circ C$, unless otherwise noted.
Supply Current, Output Enabled vs. Input Voltage



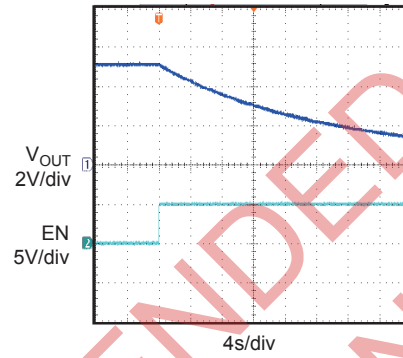
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

$V_{IN} = 5V$, $V_{EN} = 0V$ for MP62180 or 5V for MP62181, $C_L = 2.2\mu F$, $T_A = +25^\circ C$, unless otherwise noted.

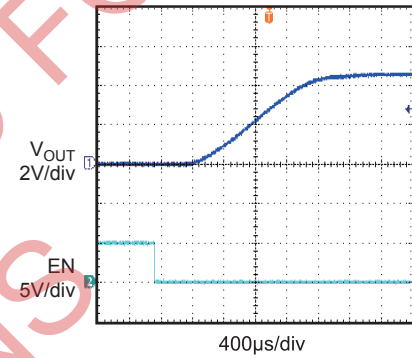
Turn On Delay and Rise Time with 0.22 μF Load
 $C_L = 0.22\mu F$



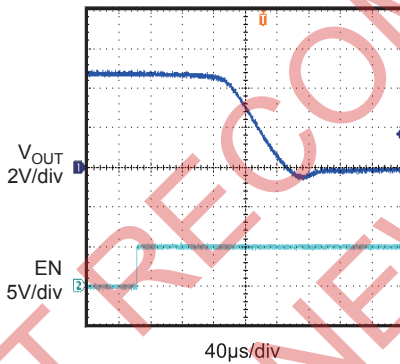
Turn Off Delay and Fall Time with 0.22 μF Load
 $C_L = 0.22\mu F$



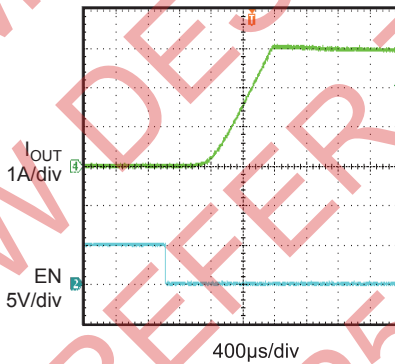
Turn On Delay and Rise Time with 2.2 μF Load
 $R_L = 2.5\Omega$



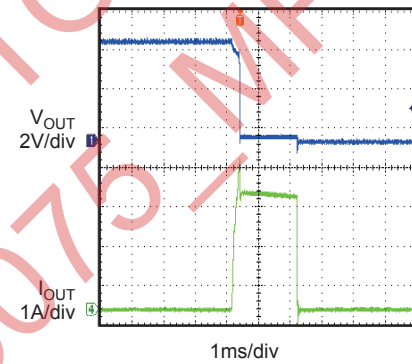
Turn Off Delay and Fall Time with 2.2 μF Load
 $R_L = 2.5\Omega$



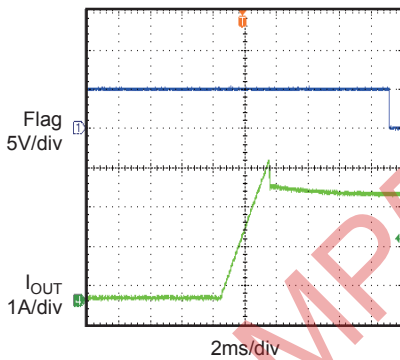
Short Circuit Current, Device Enabled into Short



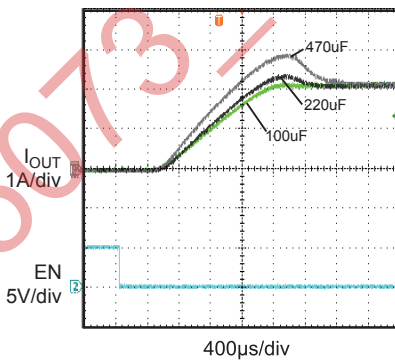
Threshold Trip Current with Ramped Load on Enabled Device



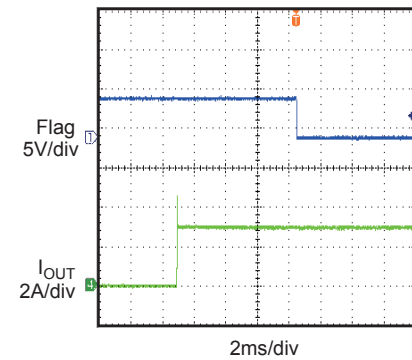
Ramped Load on Enabled Device



Inrush Current with Different Load Capacitance
 $R_L = 2.5\Omega$



1 Ω Load Connected to Enabled Device



Thermal Protection

The purpose of thermal protection is to prevent damage in the IC by allowing excessive current to flow and heating the junction. The die temperature is internally monitored until the thermal limit is reached. Once this temperature is reached, the switch will turn off and allow the chip to cool. The switch has a built-in hysteresis.

Under-voltage Lockout (UVLO)

This circuit is used to monitor the input voltage to ensure that the MP62180/MP62181 is operating correctly.

This UVLO circuit also ensures that there is no operation until the input voltage reaches the minimum spec.

Enable

The logic pin disables the switch to reduce overall supply current. Once the EN pin reaches logic enable threshold, the MP62180/MP62181 is enabled.

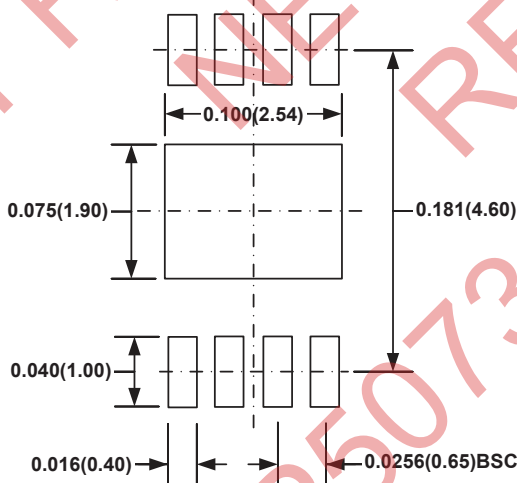
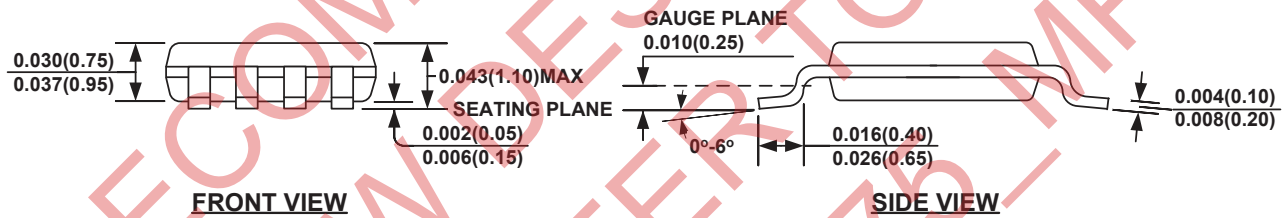
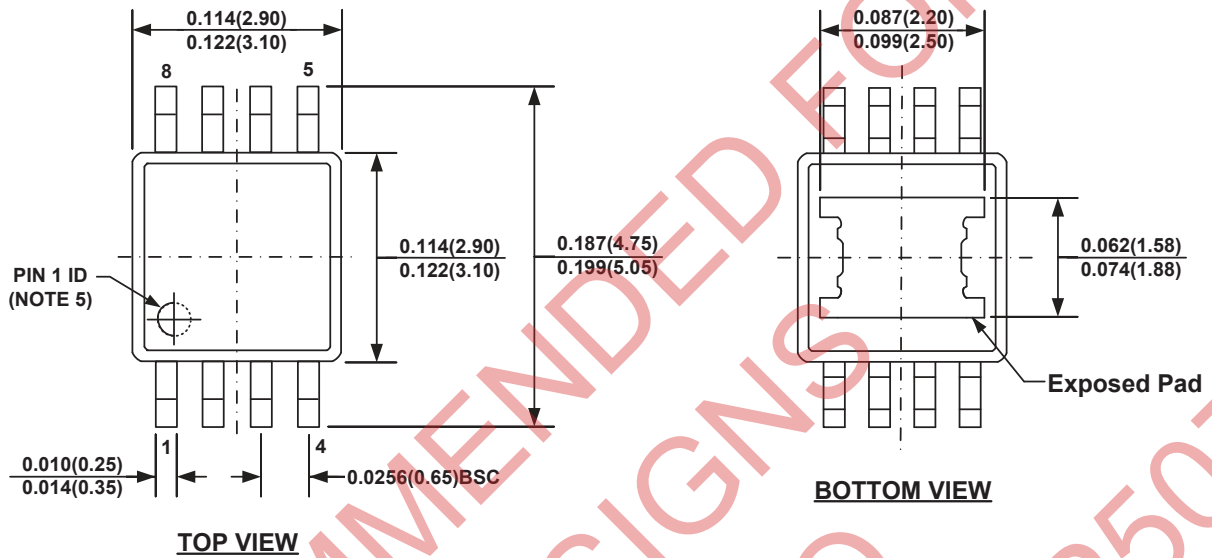
APPLICATION INFORMATION

Power-Supply Considerations

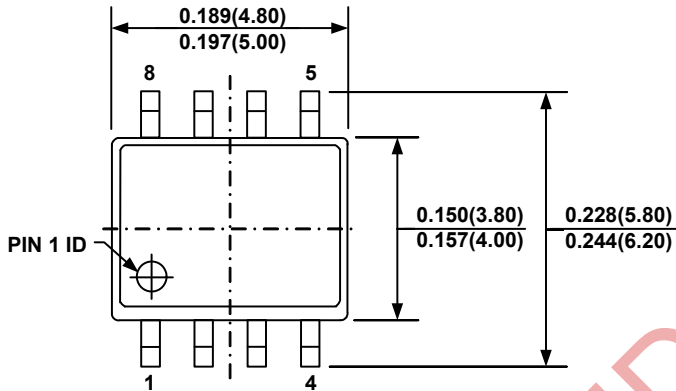
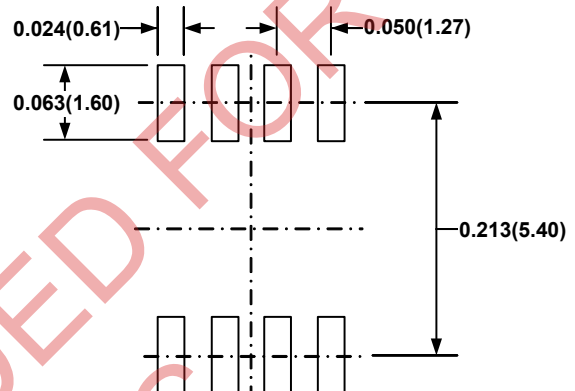
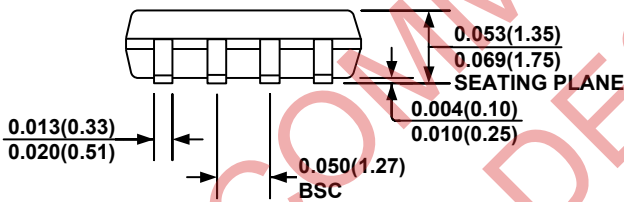
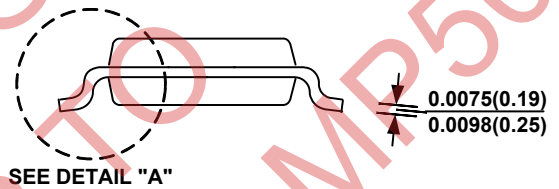
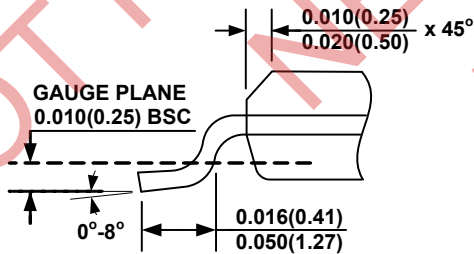
Over 10 μ F capacitor between IN and GND is recommended. This precaution reduces power-supply transients that may cause ringing on the input and improves the immunity of the device to short-circuit transients.

In order to achieve smaller output load transient ripple, placing a high-value electrolytic capacitor on the output pin(s) is recommended when the load is heavy.

NOT RECOMMENDED FOR
NEW DESIGNS
REFER TO
MP5073_MP5075_MP5075L

PACKAGE INFORMATION
MSOP8E (EXPOSED PAD)

NOTE:

- 1) CONTROL DIMENSION IS IN INCHES. DIMENSION IN BRACKET IS IN MILLIMETERS.
- 2) PACKAGE LENGTH DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR.
- 3) PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
- 4) LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.004" INCHES MAX.
- 5) PIN 1 IDENTIFICATION HAS HALF OR FULL CIRCLE OPTION.
- 6) DRAWING MEETS JEDEC MO-187, VARIATION AA-T.
- 7) DRAWING IS NOT TO SCALE.

SOIC8

TOP VIEW

RECOMMENDED LAND PATTERN

FRONT VIEW

SIDE VIEW

DETAIL "A"
NOTE:

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- 3) PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.
- 4) LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.004" INCHES MAX.
- 5) DRAWING CONFORMS TO JEDEC MS-012, VARIATION AA.
- 6) DRAWING IS NOT TO SCALE.

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